C2330

Conductor

Description

C2330 is a silver/palladium (3:1) high solids conductor paste designed for hybrid applications utilizing aluminium nitride. It exhibits good solderability and excellent adhesion.

Key Features

- Excellent solderability Excellent adhesion to aluminum nitride (AlN)

This picture does not show the packaging of C2330 and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.

Typical Properties	
Viscosity	150 – 220 Pa·s, Brookfield HBT DVIII, SC4-14 spindle & 6R utility cup @ 10 rpm, 25°C
Conductivity	30-40 milliohms/square at 15 um fired film thickness
Solids	83.0 ± 1.0%
Alloy Ratio	3 : 1
Color	Dark Grey
Resistivity	30 – 40 mΩ/□ at 15 µm fired film thickness
Solderability	Sn62/Pb36/Ag2 at 230 °C, RMA flux > 95% coverage for 5 second dip SAC305 at 250 °C, RMA flux 100% coverage for 5 second dip

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Recommended Processing Guide	
Printing Parameters	280 mesh stainless steel screen
Drying Temperature	150 °C peak tempera-tureDwell time for 10 to 15 minutes
Process Temperature (TDS)	850 °C peak tempera-tureDwell time for 10 minutes
Film Thickness	Wet: 34 – 38 µmDried: 22 – 26 µmFired: 13 – 16 µm
Recommended Thinner	Heraeus RV-372

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Version (last updated) 21 Aug 2026

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Warranty

Material guaranteed to meet specifications for 6 months from date of manufacturing with proper storage.

Storage

Store in a dry location at 20 – 25°C. DO NOT REFRIGERATE. Allow paste to come to room temperature prior to opening. Spatulate well before using, as settling may occur during storage.

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